

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2022/0386451 A1 WU et al.

Dec. 1, 2022 (43) **Pub. Date:**

(54) INTERCONNECT STRUCTURE HAVING CONDUCTOR EXTENDING ALONG DIELECTRIC BLOCK

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(21) Appl. No.: 17/884,418

(22) Filed: Aug. 9, 2022

Related U.S. Application Data

(60) Continuation of application No. 17/025,887, filed on Sep. 18, 2020, now Pat. No. 11,457,525, which is a continuation of application No. 15/723,099, filed on Oct. 2, 2017, now Pat. No. 10,785,865, which is a division of application No. 15/016,147, filed on Feb. 4, 2016, now Pat. No. 9,807,867.

Publication Classification

(51) Int. Cl. H05K 1/02 (2006.01)H01L 21/768 (2006.01)(2006.01)H01L 21/48

H01L 23/498	(2006.01)
H01L 23/552	(2006.01)
H05K 1/11	(2006.01)
H05K 3/00	(2006.01)
H05K 3/40	(2006.01)
H05K 3/42	(2006.01)

(52) U.S. Cl.

CPC H05K 1/0216 (2013.01); H05K 1/024 (2013.01); H01L 21/76805 (2013.01); H05K 1/0222 (2013.01); H01L 21/485 (2013.01); H01L 21/486 (2013.01); H01L 23/49827 (2013.01); H01L 23/552 (2013.01); H05K 1/113 (2013.01); H05K 1/115 (2013.01); H05K 3/0047 (2013.01); H05K 3/4007 (2013.01); H05K 3/423 (2013.01); H05K 1/0245 (2013.01); H05K 3/42 (2013.01); H05K 2201/0959 (2013.01); Y10T 29/49165 (2015.01); H05K 3/4038 (2013.01); H05K 2201/0723 (2013.01); H05K 2201/09545 (2013.01); H05K 2201/09645 (2013.01)

(57)**ABSTRACT**

An interconnect structure includes a first conductor, a second conductor, a dielectric block, a substrate, and a pair of conductive lines. The first conductor and the second conductor form a differential pair design. The dielectric block surrounds the first conductor and the second conductor. The first conductor is separated from the second conductor by the dielectric block. The substrate surrounds the dielectric block and is spaced apart from the first conductor and the second conductor. The pair of conductive lines is connected to the first conductor and the second conductor, respectively, and extends along a top surface of the dielectric block and a top surface of the substrate.



